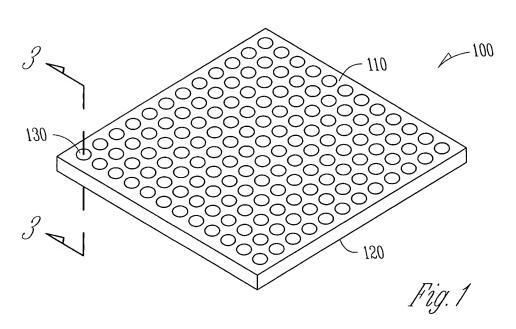
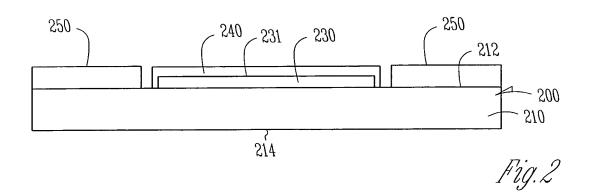
TITLE: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE INVENTOR NAME: Kum F. Leong et al.

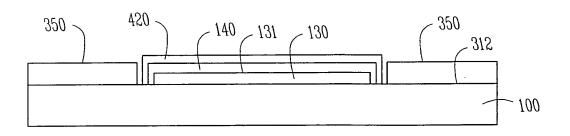
SERIAL NO.: 10/673,605











TITLE: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE INVENTOR NAME: Kum F. Leong et al.

SERIAL NO.: 10/673,605

2/4

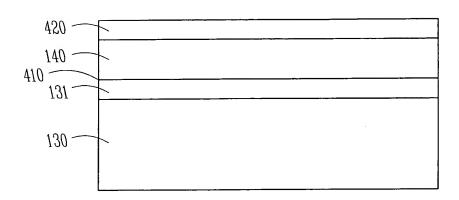
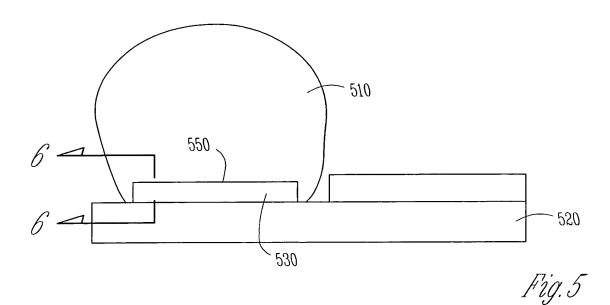
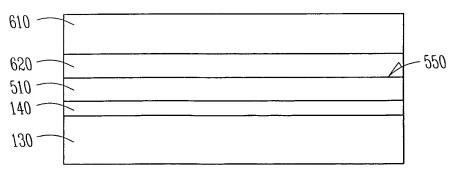


Fig. 4

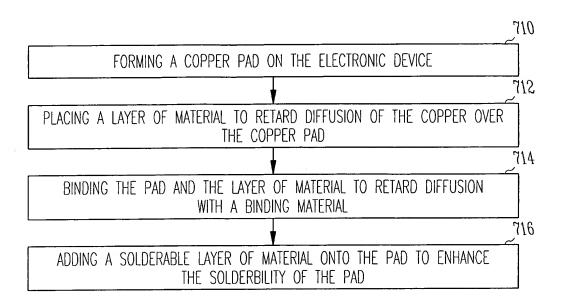




TITLE: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE INVENTOR NAME: Kum F. Leong et al.

SERIAL NO.: 10/673,605

3/4



TITLE: DIFFUSION BARRIER LAYER FOR LEAD FREE PACKAGE SUBSTRATE INVENTOR NAME: Kum F. Leong et al.

SERIAL NO.: 10/673,605

4/4

